

Abstract of the Disclosure:

An electronic component includes a semiconductor chip that has an active upper side with integrated circuits and a passive rear side. The rear side and the side border regions of the semiconductor chip also form the outer package sides of the electronic component. At least the corner regions and the edge regions of the rear side and the side border regions of the semiconductor chip have a plastic coating with a thickness in the micrometer range. Furthermore, the invention relates to a method of producing such an electronic component.

MPW/vs